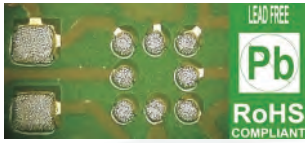


TECHNOLOGY / ALL PRODUCTS WITH LEAD OR **LEAD FREE (RoHS)**

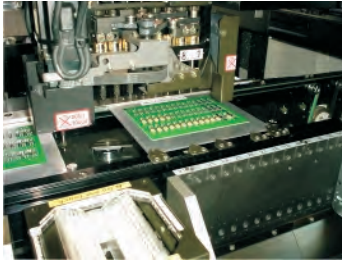
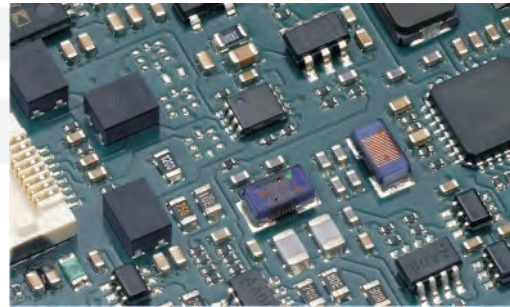


## SOLDER PASTE APPLICATION

PRINTING WITH MASK OR SILK SCREEN  
DISPENSING.

## SUBSTRATES

THICK FILM CERAMIC  
FR4, FR5, G10, G11, ROGERS  
FLEX, RIGID FLEX, IMS  
PYREX  
...



## COMPONENTS APPLICATION

UP TO 20'000 COMPONENTS/HOUR  
POSITIONING ACCURACY: +/- 50µm

9 MILLION COMPONENTS IN 2008

**HYBRID SA** IS ABLE TO PERFORM SURFACE MOUNTED ELECTRONIC COMPONENTS ON SINGLE OR DOUBLE SIDED SUBSTRATES. REFERENCES FOR STANDARDS ARE:

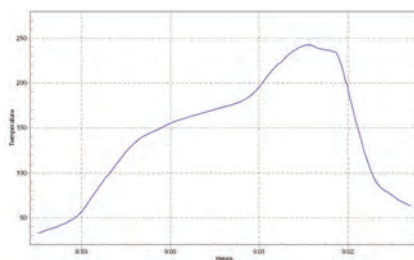
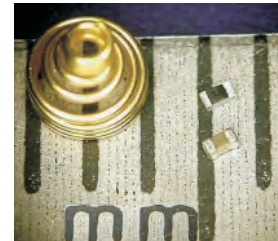
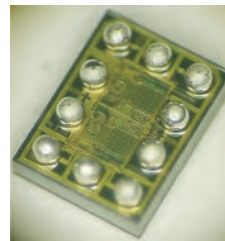
IPC/JEDEC J-STD-020D AND IPC-A-610 CLASS 3 IS APPLIED AS STANDARD.

## COMPONENTS TYPES

STANDARD BOXES, FROM "0201"  
STANDARD IC & PLCC, QFN, BGA, CSP,  
FLIP-CHIP SOLDER BUMP.

## EXOTIC COMPONENTS

TRANSFOS, COIL, CONICAL SPRINGS, QUARTZ,  
CONTACTS BATTERY, ETC...



## REFLOW

CONVECTION OVEN WITH CONVEYOR BELT

## WASHING

FULLY AUTOMATIC WASHING SYSTEM  
VAPOR PHASE RINING

